		.÷.
ì	8	1

1 1.	Number	Hits	Search Text	T	
1	Mumber	113		DB	Time stamp
-		113		USPAT;	2004/05/12 19:05
		]	or IC) and (flow\$4 or injet\$3 or drop\$4 or	US-PGPUB;	l
١.			insert\$3) with (adhesive or glue)	EPO; JPO;	
1			·	DERWENT;	
				IBM TDB	
2		142		USPAT;	2004/05/12 19:11
İ			or IC) and (flow\$4 or injet\$3 or drop\$4 or	US-PGPUB;	2001,00,12 13.11
			insert\$3) with (adhesive or glue)	EPO; JPO;	
			(autionation of gracy	DERWENT;	İ
İ			· ·	1	1
3		175	(438/108 or 438/109) and (semiconductor or	IBM_TDB	
	•	1/3	(430/100 Or 430/109) and (semiconductor or	USPAT;	2004/05/12 19:11
`		ĺ	die or chip or IC) and (flow\$4 or injet\$3	US-PGPUB;	
-			or drop\$4 or insert\$3) with (adhesive or	EPO; JPO;	
			glue)	DERWENT;	1
			,	IBM TDB	
-		920	(pad) with (top or upper) near surface	USPAT	2004/05/11 14:22
			with (semiconductor or die or chip) same		
			(pad) with (bottom or lower) near surface		
	-	-	with (semiconductor or die or chip)		1
_		1	"4127321".PN.	USPAT	2004/05/11 14:11
l _		1	"4796977".PN.	1	
l _		1	"4867543".PN.	USPAT	2004/05/11 14:11
		_		USPAT	2004/05/11 14:12
-		1	"5073010".PN.	USPAT	2004/05/11 14:12
-		1	"5130830".PN.	USPAT	2004/05/11 14:12
-		1	"5221989".PN.	USPAT	2004/05/11 14:12
-		1	"5381307".PN.	USPAT	2004/05/11 14:12
-	ĺ	6	"5497258"	USPAT	2004/05/11 14:21
-		125	(pad) with both near surface with	USPAT	2004/05/11 14:33
			(semiconductor or die or chip)		2001/03/11 14:33
		0	"20030205814"	USPAT	2004/05/11-14:34
_		1	"20030205814"		
İ		_	20030203014	USPAT;	2004/05/11 14:42
_		1	W.C.E.O.E.O.A.II	US-PGPUB	
-		1	"6559584"	USPAT;	2004/05/11 14:39
]		_ '		US-PGPUB	
-		3	"6559548"	USPAT;	2004/05/11 14:39
				US-PGPUB	·
-	•	1	"20030205814" and material with (first or	USPAT;	2004/05/11 14:59
	. [	·	second)	US-PGPUB	
l –	-	1	"5939789".PN.	USPAT	2004/05/11 14:50
_		1	"6211569".PN.	USPAT	2004/05/11 14:56
l _		1	"6452274".PN.	USPAT	
_	1	1	"6534870".PN.		2004/05/11 14:57
_ `	ľ	1	"6559548".PN.	USPAT	2004/05/11 14:58
l _		- 1		USPAT	2004/05/11 14:58
-	. 1	57	"5539652"	USPAT;	2004/05/11 15:56
	ĺ			US-PGPUB .	
_		12709	(semiconductor or die or chip or IC) and	USPAT;	2004/05/12 15:22
	- 1	l	(flow\$4 or injet\$3 or drop\$4 or insert\$3)	US-PGPUB	
	ľ		with (adhesive or glue)		
-		6041	(semiconductor or die or chip or IC) and	USPAT;	2004/05/11 16:19
			(flow\$4 ) with (adhesive or glue)	US-PGPUB	
_	i	1605	(semiconductor or die or chip or IC) and	USPAT;	2004/05/11 16:20
*		= 7	(flow\$4) near (adhesive or glue)	US-PGPUB	2004/03/11 16:20
_		1208	(semiconductor or die or chip or IC) and		2004/05/10 12 00
-		1200	(flow\$4) near (adhesive or glue)	USPAT	2004/05/12 13:23
		3	//somiconductor or discretification To		0004/05/55 55
_		ا د	((semiconductor or die or chip or IC) and	USPAT	2004/05/11 16:23
			(flow\$4 ) near (adhesive or glue)) and		
	ļ	1	(semiconductor or die or chip or IC) with		
			small with (flow\$4 ) near (adhesive or		
			glue)		
_		0 ]	((semiconductor or die or chip or IC) and	USPAT	2004/05/11 16:23
_		Ĭ	(flow\$4 ) near (adhesive or glue)) and	;	
-	İ		(semiconductor or die or chip or IC) with		·
		1	gab with (flow\$4 ) near (adhesive or glue)		
_	[	9	((semiconductor or die or chip or IC) and	IICDAM	2004/05/11/15
	- 1	1	(flows4 ) poor (adhering or alumi) and	USPAT	2004/05/11 16:24
	. [.		(flow\$4) near (adhesive or glue)) and		
			(semiconductor or die or chip or IC) with		
. 10.			gap with (flow\$4 ) near (adhesive or glue)	and the second second second second	the second second second second second second

_					•
-		27		USPAT	2004/05/11 16:30
			(flow\$4 ) near (adhesive or glue)) and		2004/03/11 10.30
-		1	(semiconductor or die or chip or IC) with		
		· ·	(gap or space) with (flow\$4) near		•
			(adhesive or glue)		
-		1		HODAM	0004/05/44
		_	(flow\$4) near (adhesive or glue)) and	USPAT	2004/05/11 16:31
			(somigondustan on dis an abi		
		Ī	(semiconductor or die or chip or IC) with	.1	
			(dam) with (flow\$4 ) near (adhesive or		
_		46	glue)		1
		40		USPAT	2004/05/11 16:37
-			(flow\$4 ) near (adhesive or glue)) and		
1	•		(semiconductor or die or chip or IC) same		
			(dam or gap or spac\$3) with (flow\$4 ) near		
ĺ			(adhesive or glue)	· ·	1
-		193		USPAT	2004/05/11 16:38
		1	(flow\$4) near (adhesive or glue)) and		1 2017, 007, 22 20.30
			(dam or gap or spac\$3) with (flow\$4 ) near		
			(adhesive or glue)		
-		147		USPAT	2004/05/11 16:38
			(flow\$4) near (adhesive or glue)) and	JOSEAN	2004/05/11 16:38
1	100	-	(dam or gap or spac\$3) with (flow\$4) near		
			(adhesive or glue)) not (((semiconductor		1
1		1	or die or chip or IC) and (flow\$4) near	1	1
		•	(adhesive or glue)) and (semiconductor or		
		1	die or chip or TC) game (semiconductor or	1	].
1			die or chip or IC) same (dam or gap or		į l
		1	spac\$3) with (flow\$4 ) near (adhesive or	,	J .
		_	glue))		1
-		0	"20020094608"	USPAT	2004/05/11 16:44
-		1	"20020094608"	USPAT;	2004/05/11 16:44
1		1.		US-PGPUB	
-	-	10		USPAT	2004/05/11 16:45
-		1	5422435.pn. and adhesive with epoxy	USPAT	2004/05/11 10:43
-	*	1208	(semiconductor or die or chip or IC) and	USPAT	2004/05/12 12:07
	•		(flow\$4 ) near (adhesive or glue)		2003/03/12 13:21
-		10	(semiconductor or die or chip or IC) and	USPAT	2004/05/12 15:22
		1	(flow\$4 ) near (adhesive or glue) same	1 35171	2004/03/12 13:22
			(underfill\$3 or under near fill\$3 or	1 .	
			under-fill)		1
-		51	(semiconductor or die or chip or IC) and	USPAT	2004/05/12 15 00
1		1	(flow\$4 or injet\$3 or drop\$4 or insert\$3)	OSEMI	2004/05/12 15:28
			with (adhesive or glue) same (underfill\$3	1	1
			or under near fill\$3 or under-fill)		
_		324	(semiconductor or die or chip or IC) and	HODAM	10004/05/50 == =
1 .		""	(flow\$4 or injet\$3 or drop\$4 or insert\$3)	USPAT	2004/05/12 15:28
			with (adhesive or alue) some (		1
1		1	with (adhesive or glue) same (encapsulat\$3		]
_		196	or mold\$3 near resin)		1
		1 20	((semiconductor or die or chip or IC) and	USPAT	2004/05/12 15:49
			(flow\$4 or injet\$3 or drop\$4 or insert\$3)		1
			with (adhesive or glue) same (encapsulat\$3		1
ĺ		1 100	or mold\$3 near resin) ) and wir\$3		1
[ -		128	((semiconductor or die or chip or IC) and	USPAT	2004/05/12 15:49
			(flow\$4 or injet\$3 or drop\$4 or insert\$3)		
1			with (adhesive or glue) same (encapsulat\$3		1
ŀ		'	or mold\$3 near resin) ) not		
		j j	(((semiconductor or die or chip or IC) and		. 1
1			(flow\$4 or injet\$3 or drop\$4 or insert\$3)		·
		]	with (adhesive or glue) same (encapsulat\$3		1
		1	or mold\$3 near resin) ) and wir\$3)		• [
-		12	"5663530"	USPAT	2004/05/12 16:09
-		1 1		USPAT	2004/05/12 16:09
-		1 1			2004/05/12 16:05
-		1 1		USPAT	2004/05/12 16:05
-		1		USPAT	2004/05/12 16:05
-		1	j	USPAT	2004/05/12 16:05
l _			•	USPAT	2004/05/12 16:06
_		1		USPAT	2004/05/12 16:06
l _				USPAT	2004/05/12 16:06
_ `			in the second second second second second second second second second second second second second second second	USPAT	2004/05/12 16:07
Ī .		1 1		USPAT	2004/05/12 16:07
_		1 1	·	USPAT	2004/05/12 16:07
_		1		USPAT	2004/05/12 16:07
		1		USPAT	2004/05/12 16:07

-	1	USPAT	2004/05/10 16 05
l <b>_</b>	40   "5376588"		2004/05/12 16:07
ļ	40 3370300	USPAT	2004/05/12 18:58
† <del>-</del>	1	USPAT	2004/05/12 16:12
<del>-</del>	1	USPAT	2004/05/12 16:12
-	1 1		
l _	1 1	USPAT	2004/05/12 16:12
ĺ	1	USPAT	2004/05/12 16:12
<u> </u>	<u>                                     </u>	USPAT	2004/05/12 16:12